



# INTERNATIONAL STANDARD

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**Universal Serial Bus interfaces for data and power -  
Part 1-2: Common components - USB Power Delivery specification**

Sample Document

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**Universal Serial Bus interfaces for data and power -  
Part 1-2: Common components - USB Power Delivery specification**

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Draft	Report on voting
100/4327/CDV	100/4380/RVC

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# *Universal Serial Bus*

## *Power Delivery Specification*

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<b><i>Revision:</i></b>	<b><i>3.2</i></b>
<b><i>Version:</i></b>	<b><i>1.1</i></b>
<b><i>Release Date:</i></b>	<b><i>2024-10</i></b>

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# Revision History

Revision	Version	Comments	Issue Date
1.0	1.0	Initial release Revision 1.0	5 July, 2012
1.0	1.1	Including errata through 31-October-2012	31 October 2012
1.0	1.2	Including errata through 26-June-2013	26 June, 2013
1.0	1.3	Including errata through 11-March-2014	11 March 2014
2.0	1.0	Initial release Revision 2.0	11 August 2014
2.0	1.1	Including errata through 7-May 2015	7 May 2015
2.0	1.2	Including errata through 25-March-2016	25 March 2016
2.0	1.3	Including errata through 11-January-2017	11 January 2017
3.0	1.0	Initial release Revision 3.0	11 December 2015
3.0	1.0a	Including errata through 25-March-2016	25 March 2016
3.0	1.1	Including errata through 12-January-2017	12 January 2017
3.0	1.2	Including errata through 21-June-2018	21 June 2018
3.0	2.0	Including errata through 29-August-2019	29 August 2019
3.1	1.0	Including errata through May 2021	May 2021
3.1	1.1	Including errata through July 2021  This version incorporates the following ECNs: <ul style="list-style-type: none"> <li>EPR Clarifications</li> <li>Define AMS starting point</li> </ul>	July 2021
3.1	1.2	Including errata through October 2021  This version incorporates the following ECNs: <ul style="list-style-type: none"> <li>Clarify use of Retries</li> <li>Battery Capabilities</li> <li>FRS timing problem</li> <li>PPS power rule clarifications</li> <li>Peak current support for EPR AVS APDO</li> </ul>	October 2021
3.1	1.3	This version incorporates the following ECNs: <ul style="list-style-type: none"> <li>Robust EPR Source Operation</li> <li>EPR Source Caps Editorial</li> <li>SRC PPS behavior in low current request</li> <li>Enter USB</li> </ul>	January 2022
3.1	1.4	Editorial changes  This version incorporates the following ECNs: <ul style="list-style-type: none"> <li>Capabilities Mismatch Update</li> <li>Chunking Timing Issue</li> <li>OT Mitigation</li> </ul>	April 2022

Revision	Version	Comments	Issue Date
3.1	1.5	Editorial changes This version incorporates the following ECNs: <ul style="list-style-type: none"> <li>• Timer Description Corrections</li> <li>• Change Source_Info Requirements</li> <li>• AMS Update</li> </ul>	July 2022
3.1	1.6	Editorial changes This version incorporates the following ECNs: <ul style="list-style-type: none"> <li>• USB4® V2 Updates</li> <li>• Data Reset Issues</li> <li>• Increase tSenderResponse</li> <li>• PPS Power Limit Bit Update</li> <li>• Support for Asymmetric Mode</li> <li>• Timer Description Corrections Revisited</li> </ul>	October 2022
3.1	1.7	Editorial Changes This version incorporates the following ECNs: <ul style="list-style-type: none"> <li>• Data Reset Invalid Reject Handling</li> <li>• Source request</li> <li>• Source Transition</li> <li>• EPR Entry</li> </ul>	January 2023
3.1	1.8	Editorial Changes This version incorporates the following ECNs: <ul style="list-style-type: none"> <li>• Slew rate exemption for Power Role Swap.</li> <li>• EUDO cable speed clarification.</li> <li>• Update to PPS Requirements.</li> <li>• Deprecate Interruptibility.</li> <li>• Section 7.3 restructure and update.</li> </ul>	April 2023
3.1	1.9	Editorial Changes	July 2023

Revision	Version	Comments	Issue Date
3.2	1.0	<p>This version incorporates the following ECNs:</p> <ul style="list-style-type: none"> <li>• VDM-use Conditions.</li> <li>• tTypeCSinkWaitCap.</li> <li>• tFirstSourceCap Clarification</li> <li>• Hard Reset Clarification.</li> <li>• Unrecognized Country Code</li> <li>• EPR Entry Process-1</li> <li>• SPR AVS Definition</li> <li>• EPR Power Rules Clarifications</li> </ul>	October 2023
3.2	1.1	<p>This version incorporates the following ECNs:</p> <ul style="list-style-type: none"> <li>• Power Transition time from EPR to PR_Swap</li> <li>• Capabilities Mismatch Update</li> <li>• Deprecate GotoMin and GiveBack Features and Update Power Reserve</li> <li>• EPR Entry requirements Clarification</li> <li>• EPRMDO and Entry Clarification.</li> <li>• Remove 10.2.4 power sharing between ports</li> <li>• Source PDP rating field clarifications</li> <li>• Source Power Rules update.</li> <li>• Source_Info Message Clarifications.</li> <li>• Correction to BMC description.</li> <li>• EPR Source cap clarification.</li> <li>• Delaying of VCONN Swap.</li> <li>• EPR_Request in SPR Mode.</li> <li>• Generic transition diagram.</li> <li>• Removing the usage of Ping message</li> <li>• Sink Standby</li> <li>• Source Info Support</li> </ul>	October 2024

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Roy Chestnut	LeCroy Corporation	Thomas Farkas	Microchip Technology Inc.
Tyler Joe	LeCroy Corporation	Venkataraman Krishnamoorthy	Microchip Technology Inc.
Phil Jakes	Lenovo	Andrew Yang	Microsoft Corporation
Do Kyun Kim	LG electronics	Anthony Chen	Microsoft Corporation
Won-Jong Choi	LG electronics	Arvind Murching	Microsoft Corporation
Won-Jong Choi	LG Electronics Ltd.	Dave Perchlik	Microsoft Corporation
Aaron Melgar	Lion Semiconductor	David Voth	Microsoft Corporation
Chris Zhou	Lion Semiconductor	Geoff Shew	Microsoft Corporation
Sehyung Jeon	Lion Semiconductor	Jayson Kastens	Microsoft Corporation
Wonyoung Kim	Lion Semiconductor	Kai Inha	Microsoft Corporation
Yongho Kim	Lion Semiconductor	Marwan Kadado	Microsoft Corporation
Dave Thompson	LSI Corporation	Michelle Bergeron	Microsoft Corporation
Alan Kinningham	Luxshare-ICT	Nathan Sherman	Microsoft Corporation
Alan Liu	Luxshare-ICT	Rahul Ramadas	Microsoft Corporation
Scott Brenden	Intel Corporation	Randy Aull	Microsoft Corporation
Sridharan Ranganathan	Intel Corporation	Shiu Ng	Microsoft Corporation
Daniel Chen	Luxshare-ICT	Tieyong Yin	Microsoft Corporation

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Toby Nixon	Microsoft Corporation	Jay Tu	Power Forest Technology Corporation
Vahid Vassey	Microsoft Corporation	Adel Lahham	Power Integrations
Vivek Gupta	Microsoft Corporation	Aditya Kulkarni	Power Integrations
Yang You	Microsoft Corporation	Akshay Nayaknur	Power Integrations
Adib Al Abaji	Molex LLC	Amruta Patra	Power Integrations
Aaron Xu	Monolithic Power Systems Inc.	K R Rahul Raj	Power Integrations
Bo Zhou	Monolithic Power Systems Inc.	Kaushik Raam	Power Integrations
Christian Sporck	Monolithic Power Systems Inc.	Rahul Joshi	Power Integrations
Di Han	Monolithic Power Systems Inc.	Ricardo Pregiteer	Power Integrations
Zhihong Yu	Monolithic Power Systems Inc.	Shruti Anand	Power Integrations
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Ben Crowe	MQP Electronics Ltd.	George Paparrizos	Qualcomm, Inc
Pat Crowe	MQP Electronics Ltd.	Giovanni Garcea	Qualcomm, Inc
Sten Carlsen	MQP Electronics Ltd.	Jack Pham	Qualcomm, Inc
Kenji Oguma	NEC Corporation	James Goel	Qualcomm, Inc
Chinjui Lin	Nexperia B.V.	Joshua Warner	Qualcomm, Inc
Max Guan	Nexperia B.V.	Karyn Vuong	Qualcomm, Inc
Stefan Seider	Nexperia B.V.	Lalan Mishra	Qualcomm, Inc
Frank Borngräber	Nokia Corporation	Nicholas Cadieux	Qualcomm, Inc
Kai Inha	Nokia Corporation	Vamsi Samavedam	Qualcomm, Inc
Pekka Leinonen	Nokia Corporation	Vatsal Patel	Qualcomm, Inc
Richard Petrie	Nokia Corporation	Chris Sporck	Qualcomm, Inc.
Sten Carlsen	Nokia Corporation	Craig Aiken	Qualcomm, Inc.
Abhijeet Kulkarni	NXP Semiconductors	Narendra Mehta	Qualcomm, Inc.
Ahmad Yazdi	NXP Semiconductors	Terry Remple	Qualcomm, Inc.
Bart Vertenten	NXP Semiconductors	Will Kun	Qualcomm, Inc.
Dennis Ha	NXP Semiconductors	Yoram Rimoni	Qualcomm, Inc.
Dong Nguyen	NXP Semiconductors	Fan-Hau Hsu	Realtek Semiconductor Corp.
Guru Prasad	NXP Semiconductors	Tsung-Peng Chuang	Realtek Semiconductor Corp.
Ken Jaramillo	NXP Semiconductors	Atsushi Mitamura	Renesas Electronics Corp.
Krishnan TN	NXP Semiconductors	Bob Dunstan	Renesas Electronics Corp.
Michael Joehren	NXP Semiconductors	Brian Allen	Renesas Electronics Corp.
Robert de Nie	NXP Semiconductors	Dan Aoki	Renesas Electronics Corp.
Rod Whitby	NXP Semiconductors	Fengshuan Zhou	Renesas Electronics Corp.
Vijendra Kuroodi	NXP Semiconductors	Hajime Nozaki	Renesas Electronics Corp.
Winston Langeslag	NXP Semiconductors	John Carpenter	Renesas Electronics Corp.
Robert Heaton	Obsidian Technology	Kiichi Muto	Renesas Electronics Corp.
Andrew Yoo	ON Semiconductor	Masami Katagiri	Renesas Electronics Corp.
Brady Maasen	ON Semiconductor	Nobuo Furuya	Renesas Electronics Corp.
Bryan McCoy	ON Semiconductor	Patrick Yu	Renesas Electronics Corp.
Christian Klein	ON Semiconductor	Peter Teng	Renesas Electronics Corp.
Cor Voorwinden	ON Semiconductor	Philip Leung	Renesas Electronics Corp.
Edward Berrios	ON Semiconductor	Steve Roux	Renesas Electronics Corp.
Michael Smith	ON Semiconductor	Tetsu Sato	Renesas Electronics Corp.
Oscar Freitas	ON Semiconductor	Toshifumi Yamaoka	Renesas Electronics Corp.
Tom Duffy	ON Semiconductor	Yimin Chen	Renesas Electronics Corp.
Brian Collins	Parade Technologies Inc.	Chunan Kuo	Richtek Technology Corporation
Craig Wiley	Parade Technologies Inc.	Heinz Wei	Richtek Technology Corporation

Max Huang	Richtek Technology Corporation	Shannon Cash	SMSC
TZUHSIEN CHUANG	Richtek Technology Corporation	Mark Bohm	SMSC
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Akihiro Ono	Rohm Co. Ltd.	William Chiechi	SMSC
Chris Lin	Rohm Co. Ltd.	Shigenori Tagami	Sony Corporation
Hidenori Nishimoto	Rohm Co. Ltd.	Shinichi Hirata	Sony Corporation
Kris Bahar	Rohm Co. Ltd.	Amanda Hosler	Specwerkz
Manabu Miyata	Rohm Co. Ltd.	Bob Dunstan	Specwerkz
Ruben Balbuena	Rohm Co. Ltd.	Brad Saunders	Specwerkz
Takashi Sato	Rohm Co. Ltd.	Diane Lenox	Specwerkz
Vijendra Kuroodi	Rohm Co. Ltd.	Michael Munn	StarTech.com Ltd.
Yusuke Kondo	Rohm Co. Ltd.	Fabien Friess	ST-Ericsson
Kazuomi Nagai	ROHM Co., Ltd.	Giuseppe Platania	ST-Ericsson
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Toni Lehimo	Salcomp Plc	Milan Stamenkovic	ST-Ericsson
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Tong Kim	Samsung Electronics Co. Ltd.	Patrizia Milazzo	ST-Ericsson
Amit Bouzaglo	Scosche Industries	Christophe Cochard	STMicroelectronics
Alvin Cox	Seagate Technology LLC	Christophe Lorin	STMicroelectronics
Emmanuel Lemay	Seagate Technology LLC	Filippo Bonaccorso	STMicroelectronics
John Hein	Seagate Technology LLC	Jessy Guilbot	STMicroelectronics
Marc Noblitt	Seagate Technology LLC	Joel Huloux	STMicroelectronics
Michael Morgan	Seagate Technology LLC	John Bloomfield	STMicroelectronics
Ronald Rueckert	Seagate Technology LLC	Massimo Panzica	STMicroelectronics
Tony Priborsky	Seagate Technology LLC	Meriem Mersel	STMicroelectronics
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Tom Farkas	Semtech Corporation	Pascal Legrand	STMicroelectronics
Ankit Garg	Siemens Industry Software Inc.	Patrizia Milazzo	STMicroelectronics
Ning Dai	Silergy Corp.	Richard O'Connor	STMicroelectronics
Wanfeng Zhang	Silergy Corp.	Morten Christiansen	Synopsys, Inc.
Kafai Leung	Silicon Laboratories, Inc.	Nivin George	Synopsys, Inc.
Kok Hong Soh	Silicon Laboratories, Inc.	Prishkit Abrol	Synopsys, Inc.
Sorin Badiu	Silicon Laboratories, Inc.	Zongyao Wen	Synopsys, Inc.
Steven Ghang	Silicon Laboratories, Inc.	Joan Marrinan	Tektronix
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Aniket Mathad	SiliConch Systems Private Limited	Matthew Dunn	Teledyne-LeCroy
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Jaswanth Ammineni	SiliConch Systems Private Limited	Anand Dabak	Texas Instruments
Jinisha Patel	SiliConch Systems Private Limited	Annamalai Kasthuri	Texas Instruments
Kaustubh Kumar	SiliConch Systems Private Limited	BIJU Erayamkot Panayamthatta	Texas Instruments
Nitish	SiliConch Systems Private Limited	Bill Waters	Texas Instruments
Pavitra Balasubramanian	SiliConch Systems Private Limited	Bing Lu	Texas Instruments
Rakesh Polasa	SiliConch Systems Private Limited	Deric Waters	Texas Instruments
Satish Anand Verkila	SiliConch Systems Private Limited	Grant Ley	Texas Instruments
Shubham Paliwal	SiliConch Systems Private Limited	Gregory Watkins	Texas Instruments
Vishnu Pusuluri	SiliConch Systems Private Limited	Ingolf Frank	Texas Instruments
John Sisto	SMSC	Ivo Huber	Texas Instruments
Ken Gay	SMSC	Javed Ahmad	Texas Instruments
Richard Wahler	SMSC	Jean Picard	Texas Instruments